

NIRMA UNIVERSITY
SCHOOL OF TECHNOLOGY, INSTITUTE OF TECHNOLOGY
M.Tech. in Electronics & Communication Engineering (VLSI Design)
M.Tech. Semester - II
Department Elective II

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Course Code	6EC166ME22
Course Title	IC Fabrication Technology

Course Learning Outcomes (CLOs):

At the end of the course, students will be able to -

1. Comprehend use of materials and parameters involved in the wafer preparation.
2. Illustrate and list the processes involved in fabrication of VLSI circuits.
3. Visualize the complete VLSI fabrication flow from wafer preparation to packaging.

Syllabus:

Teaching Hours:45

UNIT I: Crystal Growth and Wafer Preparation	05
Introduction, electronic grade silicon, material properties, crystal growth, silicon shaping, clean room	
UNIT II: Epitaxy	05
Introduction, wafer-phase epitaxy, molecular beam epitaxy, silicon on insulator, epitaxial evaluation	
UNIT III: Oxidation	10
Thin oxides, peroxidation cleaning, dry and wet oxidation, high pressure oxidation, oxidation of polysilicon, oxidation induced defects	
UNIT IV: Lithography	05
Lithography techniques: optical lithography, electron beam lithography, ion beam lithography, comparisons of lithography techniques	
UNIT V: Doping, Diffusion and Ion Implantation	10
Doping technology, Deposition of films using chemical vapour deposition (CVD), Low pressure chemical vapour deposition LPCVD and Sputtering Techniques, ion implantation techniques	
UNIT VI: Device and Circuit Fabrication	05
Isolation, self-alignment, metallization, NMOS IC technology, CMOS IC technology, Advancement in IC fabrication technology including 3D IC	
UNIT VII: Packaging	05
Package types, packaging design consideration, package fabrication technology, advanced packaging	

Self-Study:

The self-study contents will be declared at the commencement of Semester. Around 10% of the questions will be asked from self-study contents.

Suggested Readings:

1. S. M. Sze, VLSI Technology, Second Edition, McGraw-Hill
2. S. K. Gandhi, VLSI Fabrication Principles, Second Edition, John Wiley & Sons
3. James Plummer, M. Deal and P.Griffin, Silicon VLSI Technology, Prentice Hall Electronics and VLSI series.